

IBIS Summit @ DAC 2005:

Library Characterization & Modeling: Issues, Recommendations and Possible Solutions

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Reality: 90nm onwards!

- All tough problems at 130nm are still here,... and there are some new ones at 90nm...

Challenges: 90nm onwards!

- Significant divergence between predicted & measured performance due to variability in process & temperature
 - Requires more complex and accurate libraries, including models for interconnect
- Chips designed with multi- V_t and multi-voltage regions
 - Requires multiple libraries
- Semiconductor processes will get more complex at 65nm ...and beyond... which will lead to...
 - Even more complex libraries

Objective

Modeling & characterization environment:

- Increased accuracy to silicon at 90nm and 65nm
- Extendable to future technology nodes
- Support new capabilities (e.g. statistical timing)
- Maintain consistent modeling methodology

Issues

- Accuracy/consistency of library models
- Gap between requirements and capability
- Cost/Expertise needed to build accurate libraries
- Existing formats cannot express modeling needs
- Design tools closely “linked” to library

Model Accuracy

Requirements:

- Table lookup (piecewise linear)
- Arbitrary polynomials
- Current source models
- User definable equations / models
- Consistency across libraries

Capability Gap

Requirements:

- Delay, power & signal integrity analysis
- Multiple voltage libraries
- Statistical modeling of process & other variations
- Electromigration

Library Cost...

Requirements:

- Automate characterization & modeling flow
- Remove manual processes
- Automate curve-fitting & model generation
- Support hierarchical characterization

Library Format

Requirements:

- Unambiguous syntax and semantics
- Supported by popular industry tools
- Independent of any specific tool
- Community control / evolution

Tool “Linkage”

Requirements:

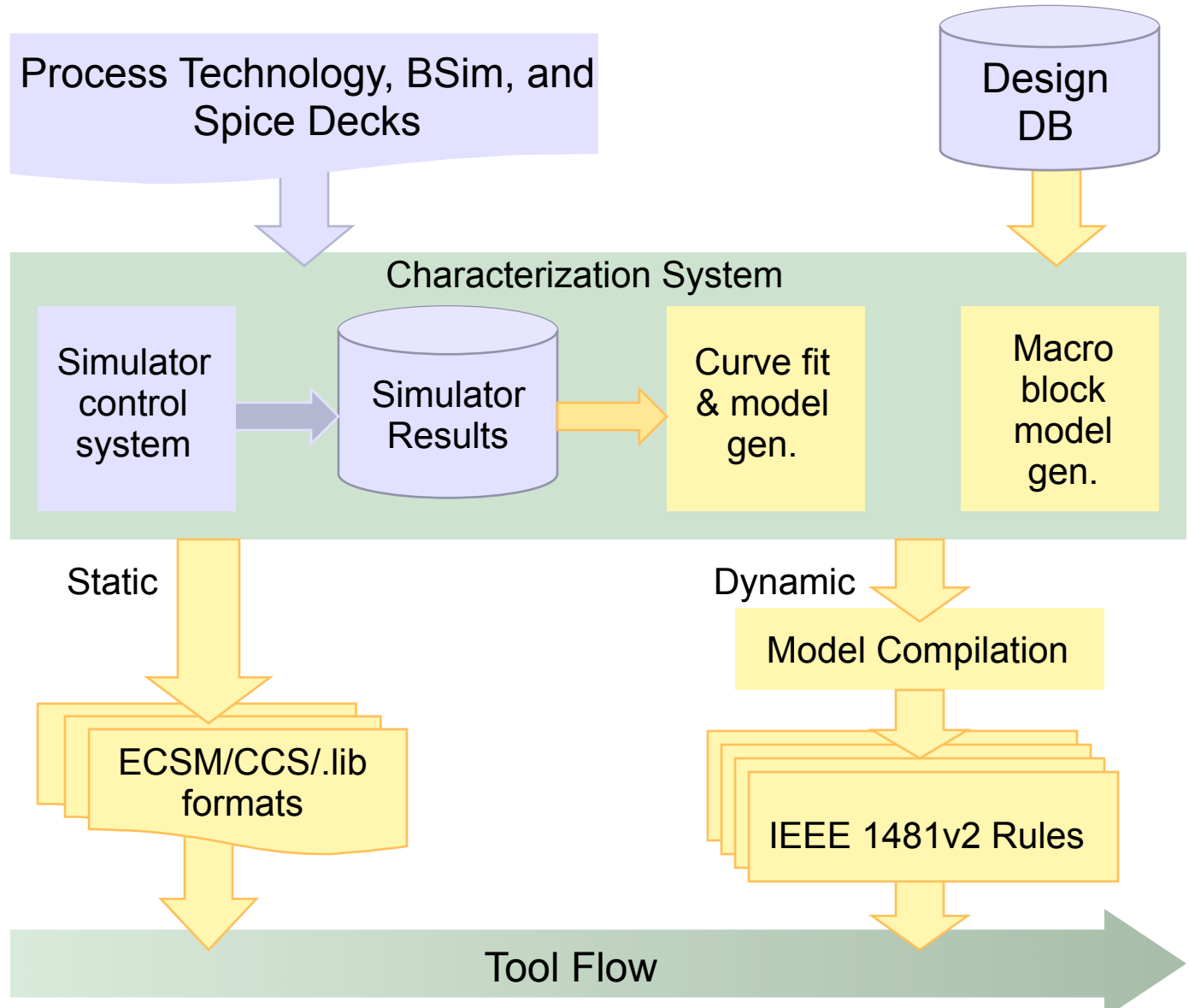
- Separation of tools from timing data / models
- API interface to modeling information
- Consistent results across all tools
- Silicon calculations defined by library provider

Roadmap

Library support for:

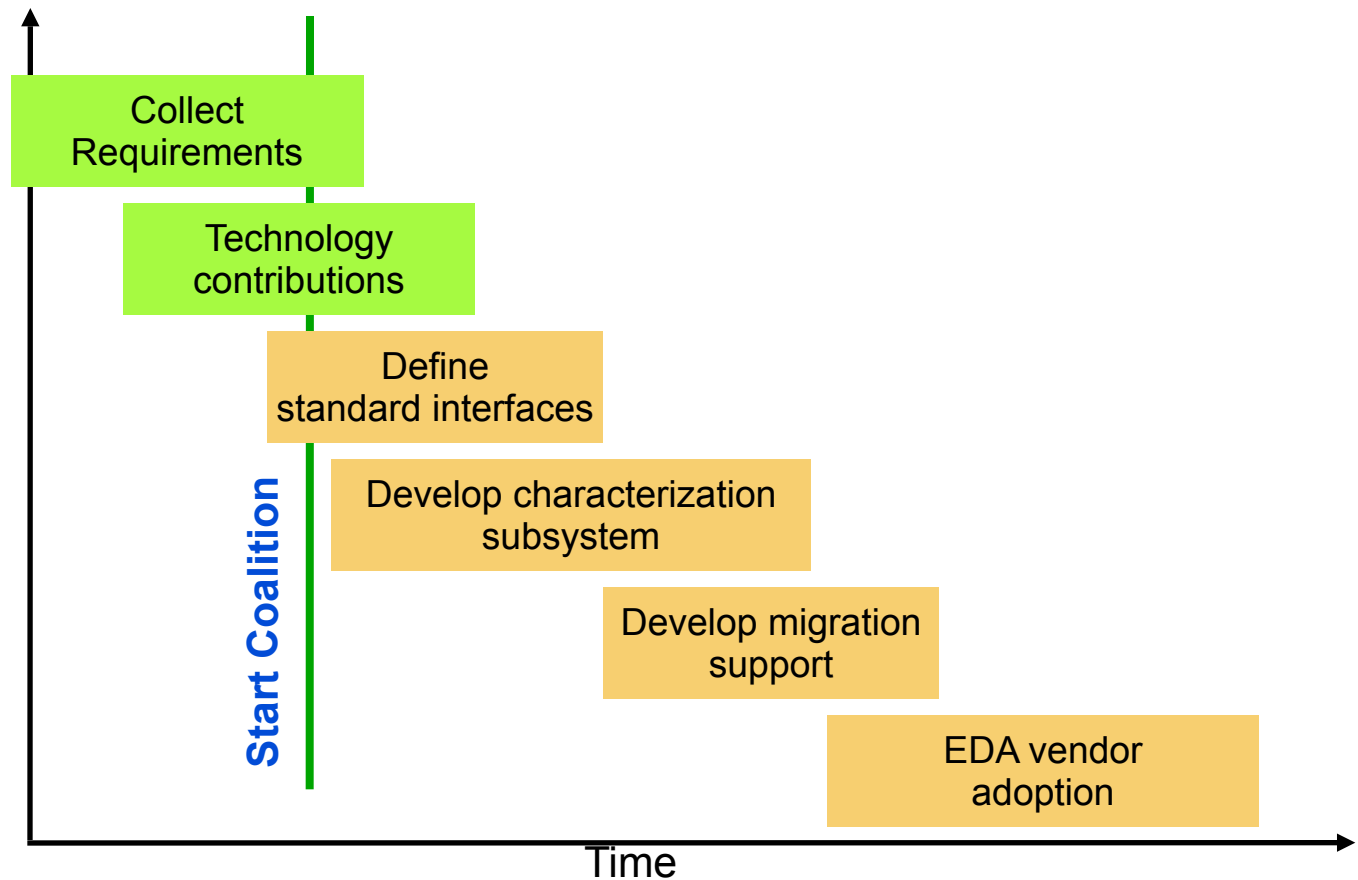
- Statistical timing
- Improved accuracy
 - Timing and noise
 - Leakage and total power
- Temp variation

Modeling System



Create New Coalition

Modeled after OpenAccess Coalition



OMC Structure

Open Modeling Coalition

- Si2 members in good standing
- Chair, Vice-Chair, Secretary
- Owners of reference flow and overall implementation
- Majority voting for decisions

Technical Steering Group

- Upto 12 members
- Led by 2 chief architects
- 2/3 super-majority voting
- Owns roadmap, implementation plans
- Charters working groups
- Appoints champions for working groups

Working Groups

- Created and disbanded by TSG
- Champion from TSG is a member
- Participants are from coalition
- Chair appointed by TSG
- Initial list of WG's:
 - Interface to modeling subsystem
 - Interface for foundry information
 - Statistical timing
 - Static formats

Targeted Participants

- ☐ Integrated device manufacturers
- ☐ Silicon foundries
- ☐ Design automation vendors
- ☐ End user companies
- ☐ IP or library vendors

Open Library Modeling Meeting

Date: June 15, 2005

Time: 10:00 – 11:30AM

Place: Anaheim Convention Center, Room 202A

Summary

- 8 Letters of intent from DTC members
- 4 companies have submitted technology
- BOD approval at April 7th meeting

Engaging industry players

Moving forward with formation of coalition

Open Modeling Meeting at DAC on 06/15